Cleaner Technology

Setting A New Standard for Microvia Reliability

In additional to CIRCUPOSIT™ 3000-1 electroless copper, which delivers industry leading interconnect reliability, Dow Electronic Materials has developed a number of cleaners to be used in conjunction with it and electrolytic plating processes to further improve microvia reliability.

RONACLEAN™ EVP-206M2 Cleaner

RONACLEAN™ EVP-206M2 Cleaner provides superior wettability and rinsability inside of the vias. This cleaner is excellent at removing Stearic Acid, glove prints, dry film residue and copper oxide. It also provides consistent performance, long bath life and minimum foaming.

Benefits

- Excellent at removing dry film residue
- Free of complexing agents
- No attack of dry film
- Ease of waste treatment

RONACLEAN™ LP-200-2 Acid Cleaners

RONACLEAN™ LP-200-2 Acid Cleaner is a one-component product, specially designed for removing residues from aqueous, alkali strippable dry films. Compatible with pattern plating processes, the bath prevents dry film attack, and eliminates ragged circuit lines and undercut at the dry film foot. It exhibits good cleaning power and wettability, combined with improved rinsability.

Benefits

- Excellent at removing developer residues associated with aqueous dry films
- Free of complexing agents
- Minimum attack of dry film
- Compatible with Dow Electronic Materials' acid copper electrolytes
- Improved rinsability
- Ease of waste treatment

		RONACLEAN™ EVP-206M2 Cleaner	RONACLEAN™ LP-200-2 Acid Cleaner
Cleaning Power	Stearic Acid	★★★★	★★★★
	Glove Prints	★★★★	★★★
	Soldermask Residue	★★★★★	★★★★
	Copper Oxide	★★★★	★★★★★
Rinsibility		★★★★★	★★★★
Soldermask Attack (with ENIG)		★★★★	★★★
Surface Tension (dynes/cm)		29	36

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